

On-Chip EM-Sensitive Interconnect Structures

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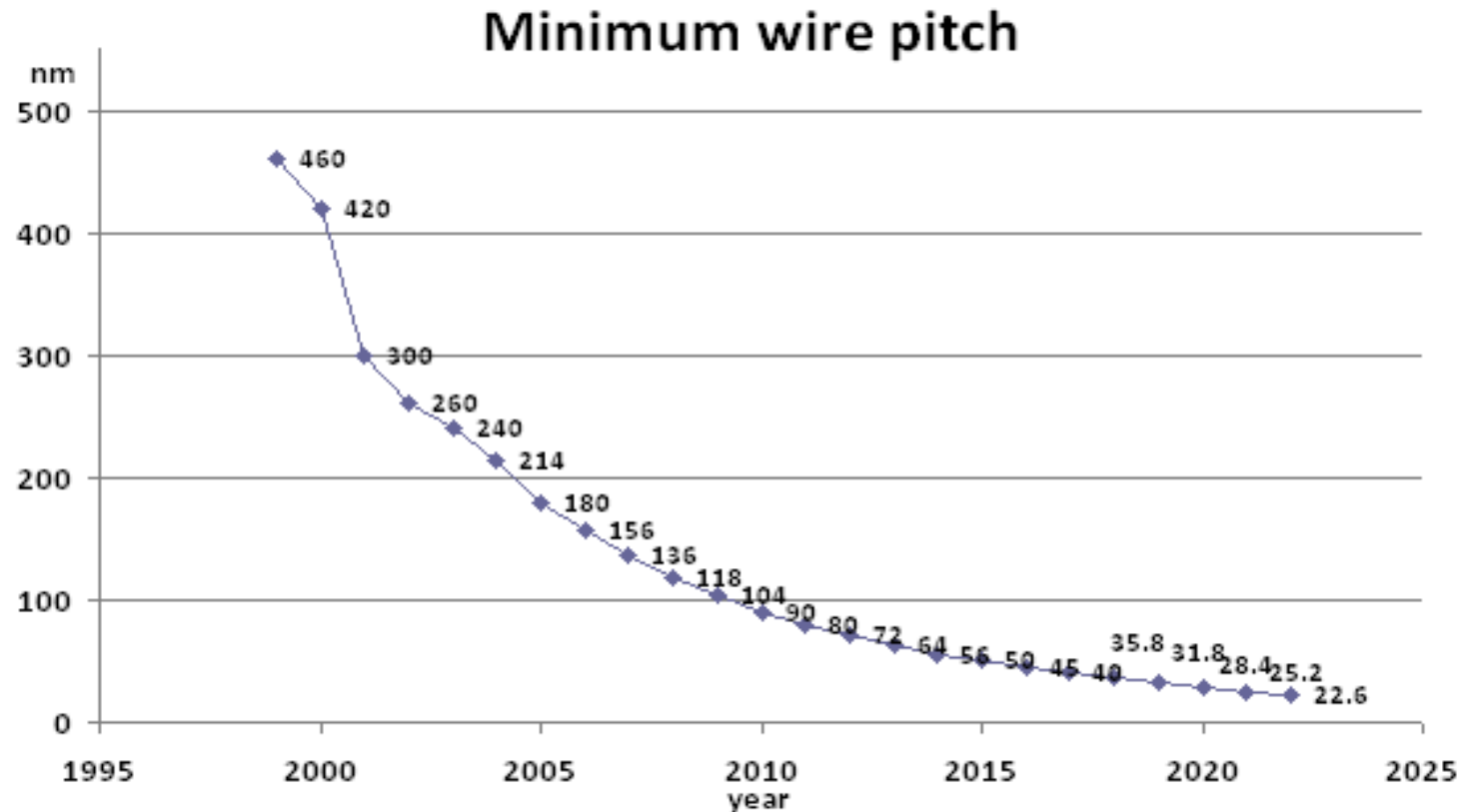
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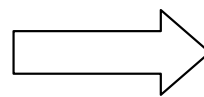
Outline

- **Introduction to EM**
- EM related effects
- EM on tri-state bus
- EM on non-tree clock
- Conclusions

Introduction to EM



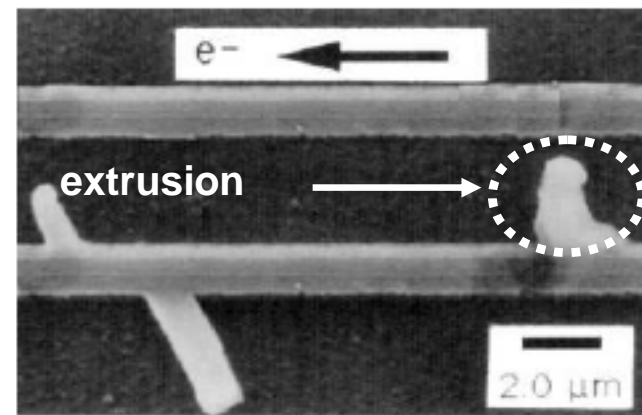
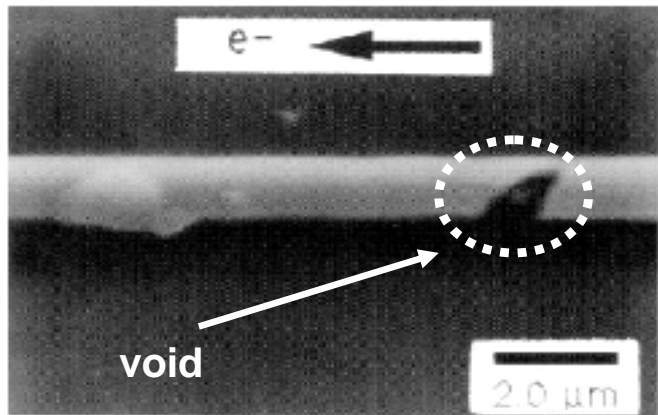
- Wire size shrinking
- Circuit complexity increasing



Current density increase

Introduction to EM

- **Electromigration:** the transport of material caused by the gradual movement of the ions in a conductor due to the momentum transfer between conducting electrons and diffusing metal atoms
- **EM failure**
 - Void
 - Extrusion



Introduction to EM

- EM lifetime projection: Black's equation

$$MTTF = \frac{A}{J^n} \cdot \exp\left(\frac{E_a}{k \cdot T}\right)$$

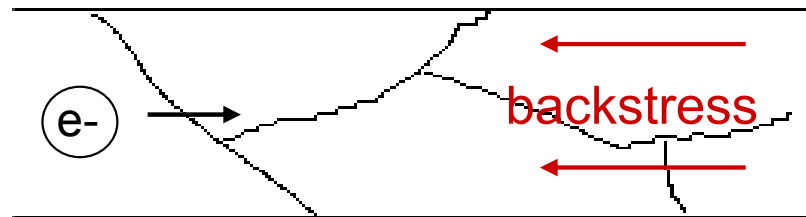
- n — current exponent, typical value 1~2
 - E_a — activation energy, typical value 1.2eV
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- **Note:** the model is abstract, not based on a physical model, but flexibly describes the failure rate dependence on the temperature, the electrical stress, and the specific technology and materials

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EM Related Effects

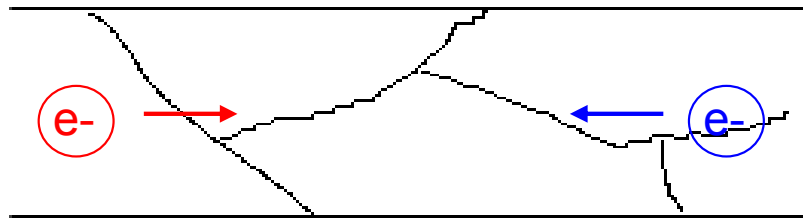
- Blech length
 - $L < L_{\text{Blech}} \implies$ immortal to EM
 - $j \cdot L < (j \cdot L)_c = \text{constant}$



- Caused by EM-induced backstress
- Typical value 10s of μms

EM Related Effects

- Self-healing
 - Caused by currents in opposite directions



- Average current recovery model

$$J_{EM,eff} = J_{ACR} = \frac{1}{T} \left[\int_0^T |j_+(t)| dt - \gamma \int_0^T |j_-(t)| dt \right]$$

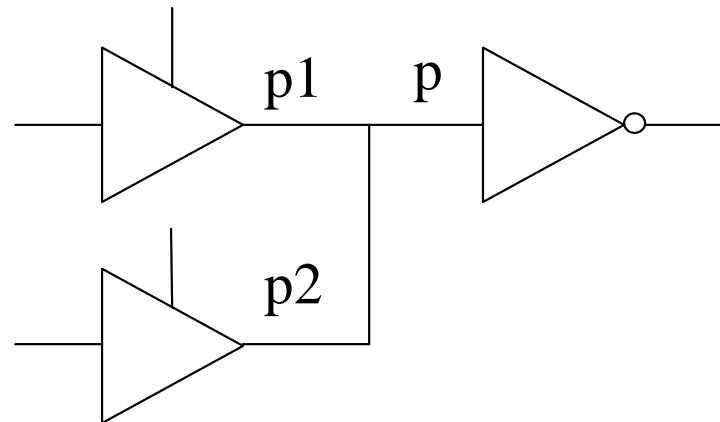
- γ — recovery coefficient, typical value 0.8~1

Outline

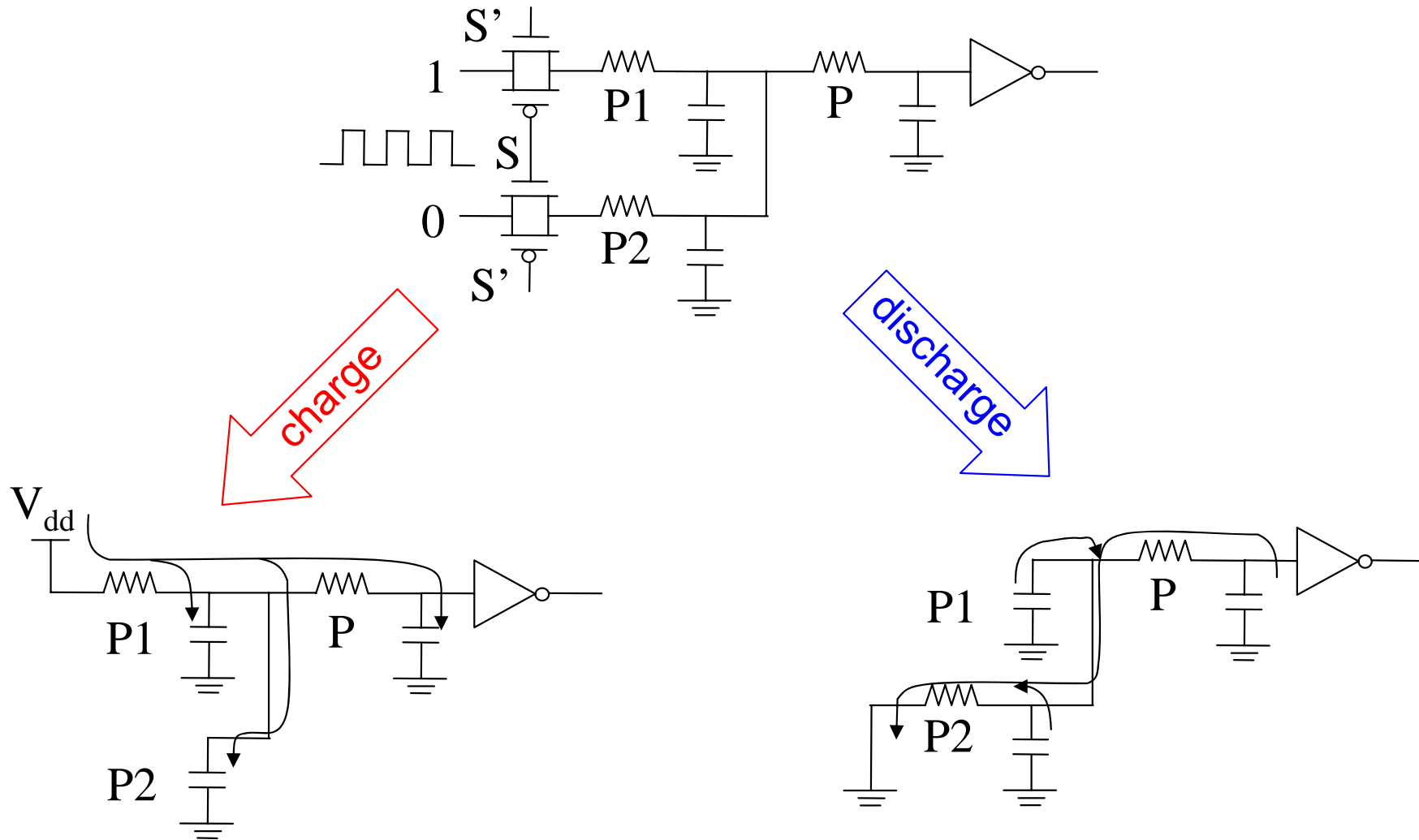
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EM on Tri-State Bus

- AC balanced condition
 - Most signal lines are in AC balanced condition: carry both positive and negative current, waveforms do not have to be the same, but the overall charge is close to zero
- **Note:** AC balanced condition is broken, if there exist different charge and discharge paths.

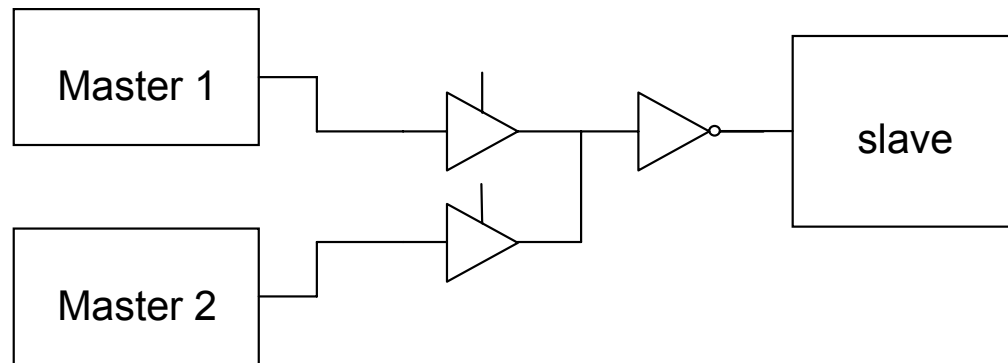


EM on Tri-State Bus



EM on Tri-State Bus

- Tri-state bus



- Circuit operation

- probability estimation: m is a critical cycle number such that if during N cycles, for m or more cycles current is unidirectional, interconnect EM failure occurs

$$P_{\geq mu} = P_{Nu} + P_{(N-1)u} + \dots + P_{mu} = \sum_{i=m}^N P_{iu}$$

$$P_{Nu} = 2[(f_{s1} \cdot f_{m10} \cdot f_{s2} \cdot f_{m21})^{N/2} + (f_{s1} \cdot f_{m11} \cdot f_{s2} \cdot f_{m2})^{N/2}]$$

EM on Tri-State Bus

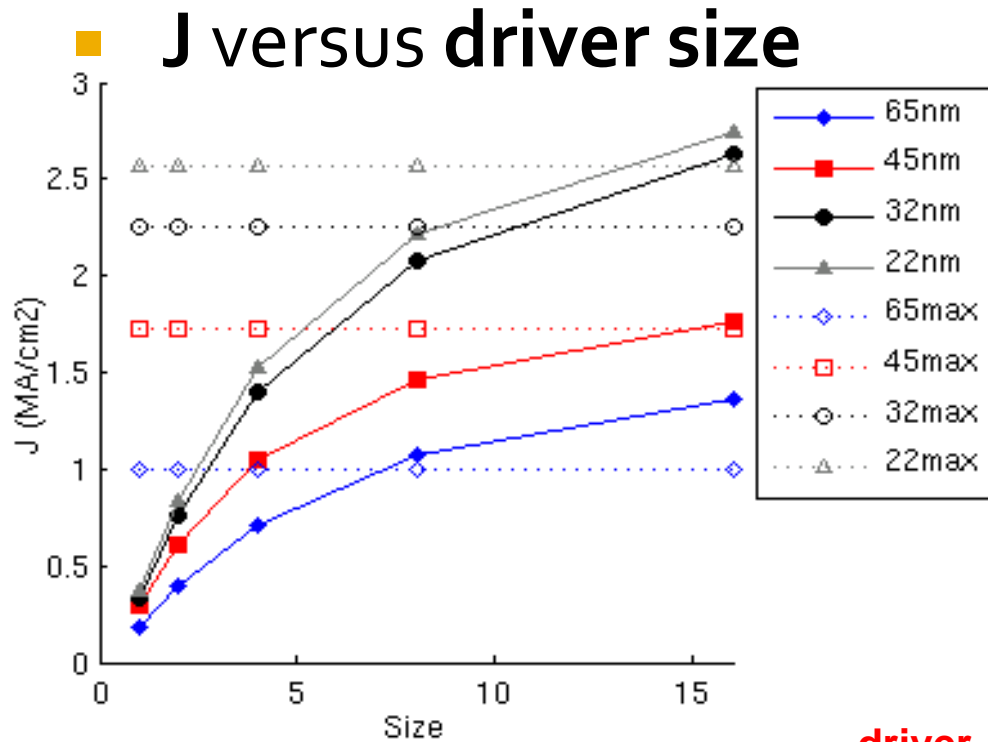
■ Wire parasitic parameters

Param Tech	w (nm)	h (nm)	r(ohm/um)	c(fF/um)	f(GHz)	T(°C)
65nm	130	104-117	3.3-3.6	0.18-0.2	0.25-1.5	105
45nm	90	72-81	7.7-8.7	0.16-0.18		
32nm	65	54-61	17.6-19.9	0.15-0.18		
22nm	45	37-42	41.5-47.1	0.13-0.16		

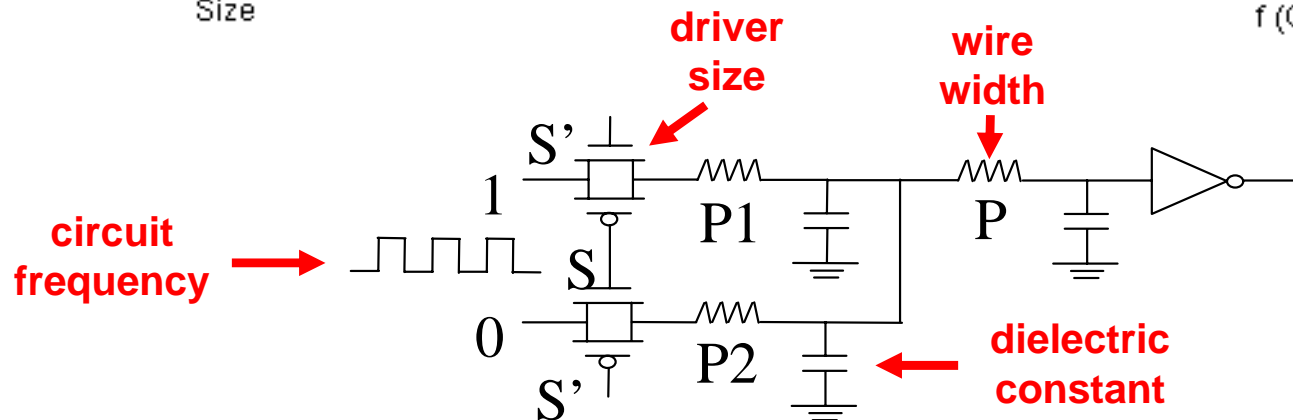
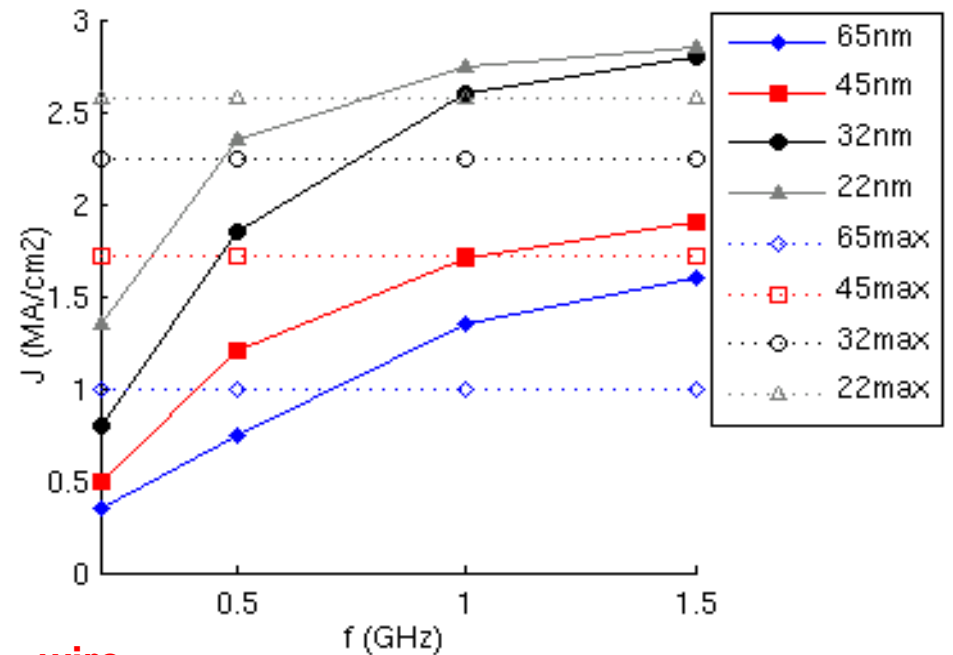
■ Sweep parameters

- Driver size
- Frequency
- Wire width
- Dielectric constant

EM on Tri-State Bus

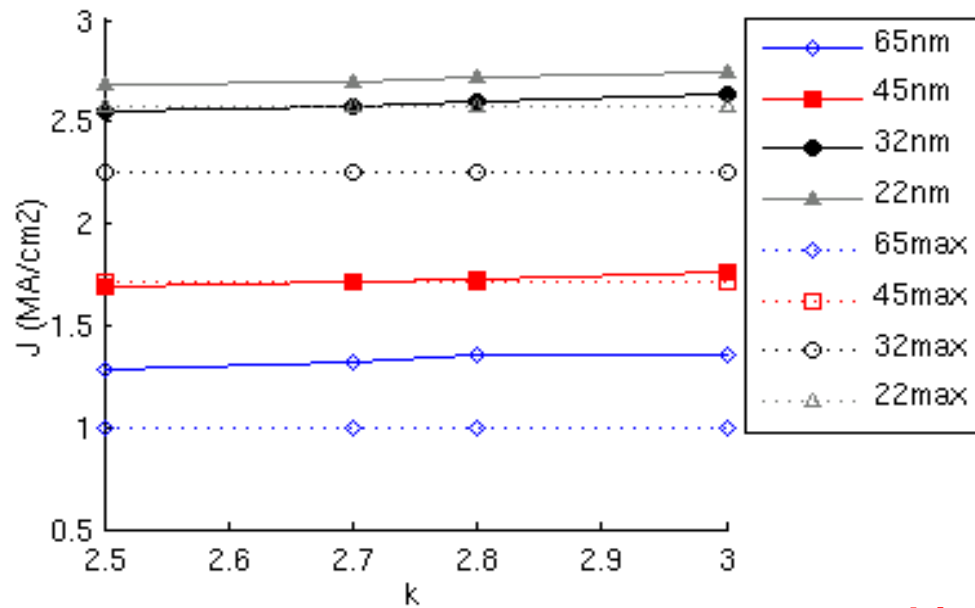


J versus circuit frequency

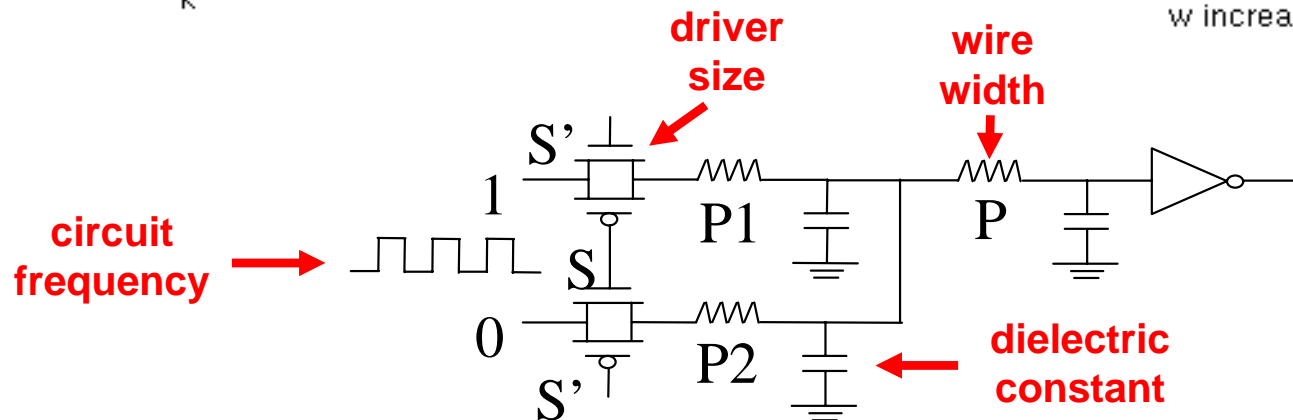
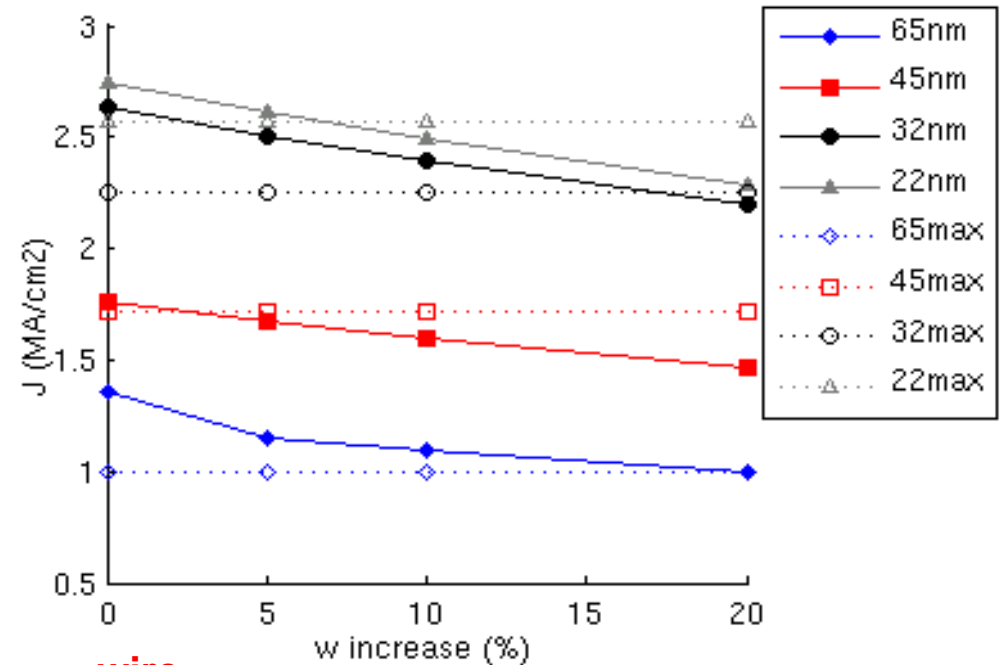


EM on Tri-State Bus

J versus dielectric constant



J versus wire width



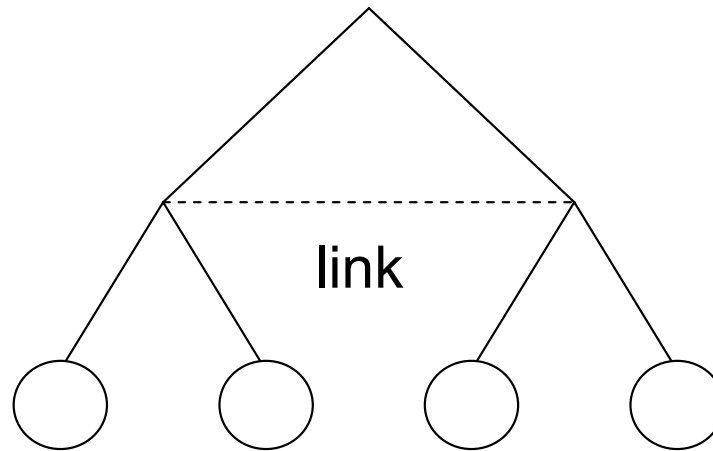
EM on Tri-State Bus

- Traditional trade offs
 - Wire width increase: simple but efficient compared to other trade offs
- New technology
 - CoWP coating
 - increase E_a at metal/cap interface
 - improve EM up to 2x
 - save additional wire budget

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EM on Non-Tree Clock



■ Advantage

- Lower skew
- Variation tolerant (timing)

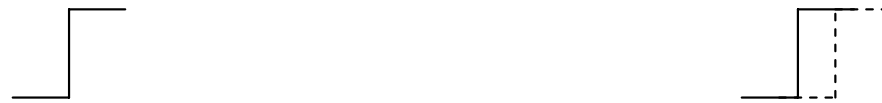
■ Disadvantage

- Extra wire length
- Reliability concerns
(connect wires with different voltage potentials)

EM on Non-Tree Clock

- Sources of voltage potential difference

- Clock skew



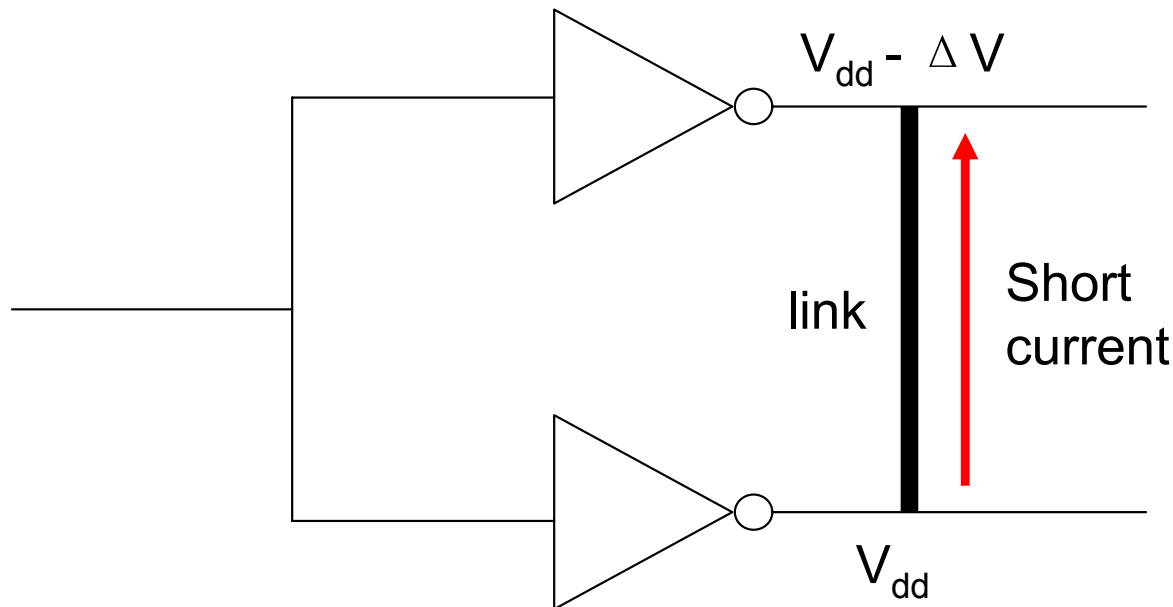
- Power noise



- Thermal effects



EM on Non-Tree Clock



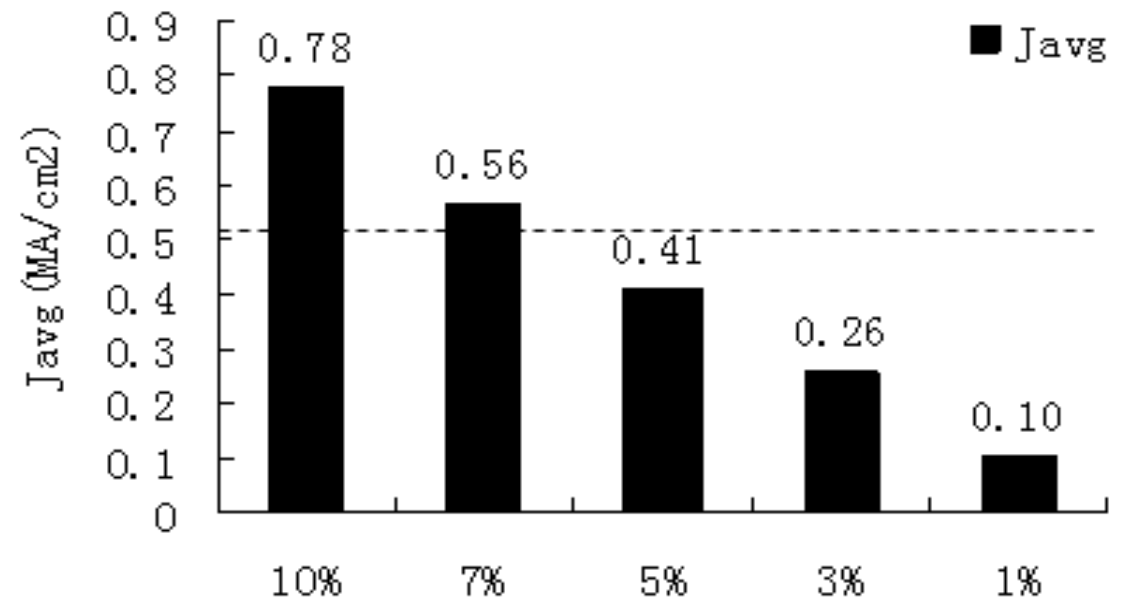
- Link failure
 - does not necessarily cause fatal malfunction but degrades performance and eliminates any advantage derived from the link

EM on Non-Tree Clock

- Non-tree/tree

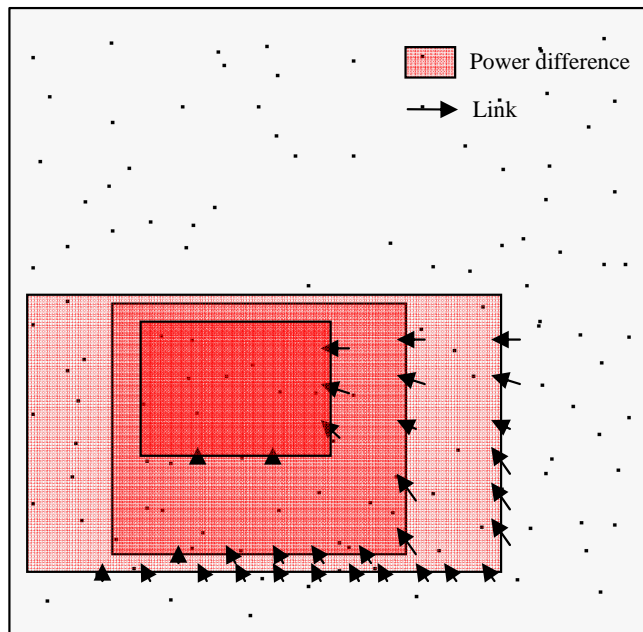
Test case	worst J_{avg} (tree) (A/cm ²)	worst J_{avg} (non-tree) (A/cm ²)	non-tree/tree ratio
r1	8.16E02	1.50E04	18x
r2	1.24E02	2.92E03	23x
r5	2.85E02	1.89E04	66x
s13207	6.89E02	9.11E04	132x
s38584	1.26E03	7.34E04	58x

- Power noise margin

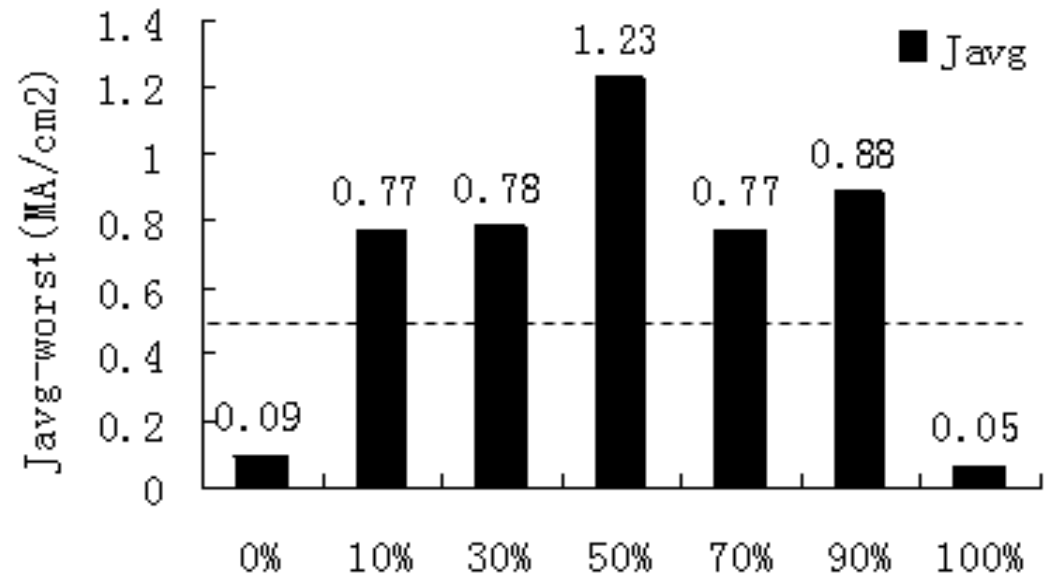


EM on Non-Tree Clock

- Links in non-tree clock across boundaries of areas with power supply difference



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Conclusions

- Summary
 - EM—dominant reliability effects
 - EM-sensitive structures
 - Tri-state bus
 - Non-tree clock
 - EM trade offs
- Future work
 - Study on EM technological solution
 - EM-aware design

Thanks for your attention!

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